

Thyristor

$$V_{RRM} = 1600V$$

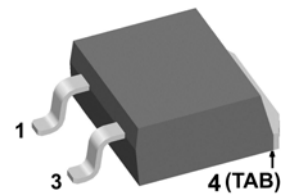
$$I_{TAV} = 30A$$

$$V_T = 1.42V$$

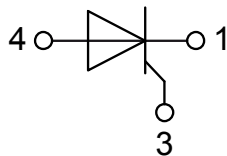
Single Thyristor

Part number

CMA30E1600PZ



Backside: anode



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

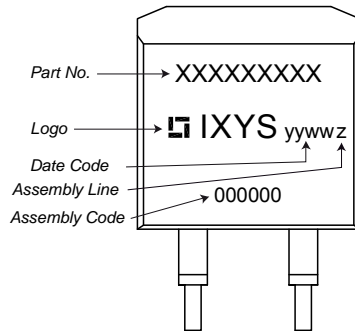
Package: TO-263 (D2Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- High creepage distance between terminals

Thyristor				Ratings							
Symbol	Definition	Conditions	min.	typ.	max.	Unit					
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}C$			1700	V					
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}C$			1600	V					
I_{RD}	reverse current, drain current	$V_{RD} = 1600 V$	$T_{VJ} = 25^{\circ}C$		10	μA					
		$V_{RD} = 1600 V$	$T_{VJ} = 125^{\circ}C$		2	mA					
V_T	forward voltage drop	$I_T = 30 A$	$T_{VJ} = 25^{\circ}C$		1.42	V					
					1.80	V					
		$I_T = 60 A$	$T_{VJ} = 125^{\circ}C$		1.42	V					
					1.92	V					
I_{TAV}	average forward current	$T_C = 115^{\circ}C$	$T_{VJ} = 150^{\circ}C$		30	A					
$I_{T(RMS)}$	RMS forward current	180° sine			47	A					
V_{T0}	threshold voltage	} for power loss calculation only	$T_{VJ} = 150^{\circ}C$		0.90	V					
r_T	slope resistance				17	m Ω					
R_{thJC}	thermal resistance junction to case				0.5	K/W					
R_{thCH}	thermal resistance case to heatsink			0.25		K/W					
P_{tot}	total power dissipation		$T_C = 25^{\circ}C$		250	W					
I_{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$	$V_R = 0 V$	260	A					
					t = 8,3 ms; (60 Hz), sine	280	A				
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 150^{\circ}C$	$V_R = 0 V$	220	A					
					t = 8,3 ms; (60 Hz), sine	240	A				
I^2t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$	$V_R = 0 V$	340	A ² s					
					t = 8,3 ms; (60 Hz), sine	325	A ² s				
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 150^{\circ}C$	$V_R = 0 V$	240	A ² s					
					t = 8,3 ms; (60 Hz), sine	240	A ² s				
C_J	junction capacitance	$V_R = 400 V$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		13	pF					
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 150^{\circ}C$		10	W					
		$t_p = 300 \mu s$			5	W					
P_{GAV}	average gate power dissipation				0.5	W					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 125^{\circ}C$; f = 50 Hz	repetitive, $I_T = 90 A$			150	A/ μs				
						$t_p = 200 \mu s$; $di_G/dt = 0.2 A/\mu s$;				500	A/ μs
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^{\circ}C$			500	V/ μs				
								$R_{GK} = \infty$; method 1 (linear voltage rise)			
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			1.3	V				
			$T_{VJ} = -40^{\circ}C$			1.6	V				
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			28	mA				
			$T_{VJ} = -40^{\circ}C$			50	mA				
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^{\circ}C$			0.2	V				
I_{GD}	gate non-trigger current					1	mA				
I_L	latching current	$t_p = 10 \mu s$	$T_{VJ} = 25^{\circ}C$			90	mA				
								$I_G = 0.2 A$; $di_G/dt = 0.2 A/\mu s$			
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^{\circ}C$			60	mA				
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^{\circ}C$			2	μs				
								$I_G = 0.5 A$; $di_G/dt = 0.5 A/\mu s$			
t_q	turn-off time	$V_R = 100 V$; $I_T = 30 A$; $V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^{\circ}C$		150	μs					
		$di/dt = 10 A/\mu s$; $dv/dt = 20 V/\mu s$; $t_p = 200 \mu s$									

Package TO-263 (D2Pak-HV)			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			35	A
T_{stg}	storage temperature		-55		150	°C
T_{VJ}	virtual junction temperature		-40		150	°C
Weight				1.5		g
F_C	mounting force with clip		20		60	N
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	4.2			mm
$d_{Spb/Apb}$		terminal to backside	4.9			mm

Product Marking



Part number

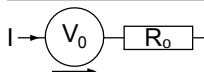
- C = Thyristor (SCR)
- M = Thyristor
- A = (up to 1800V)
- 30 = Current Rating [A]
- E = Single Thyristor
- 1600 = Reverse Voltage [V]
- PZ = TO-263AB (D2Pak) (2HV)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CMA30E1600PZ	CMA30E1600PZ	Tape & Reel	800	513695

Equivalent Circuits for Simulation

* on die level

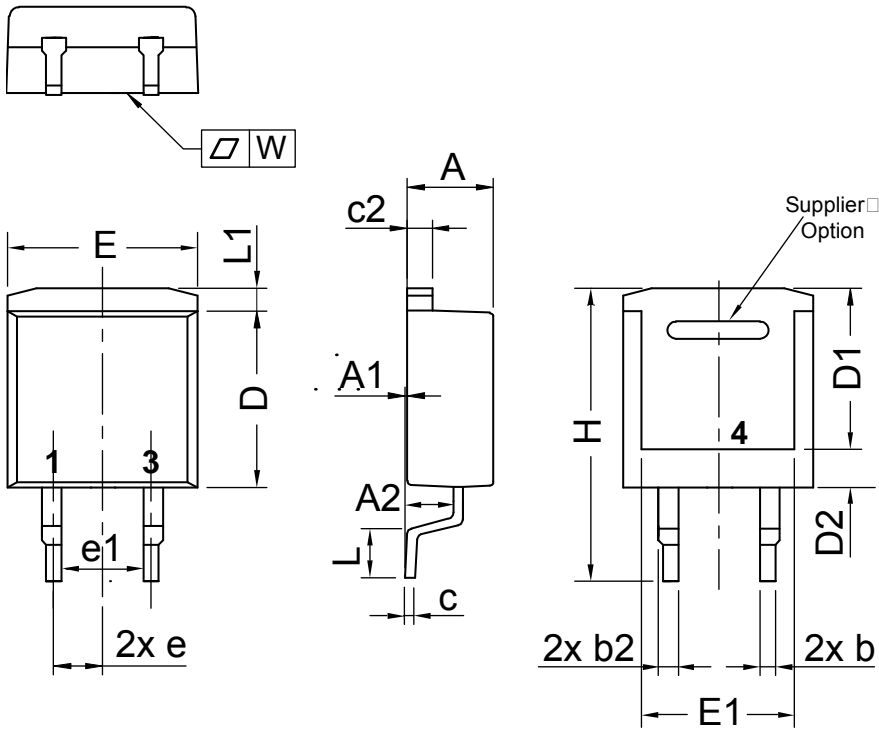
$T_{VJ} = 150^{\circ}\text{C}$



Thyristor

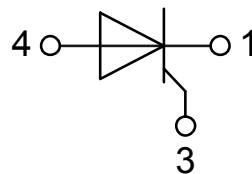
$V_{0\max}$	threshold voltage	0.9	V
$R_{0\max}$	slope resistance *	14	mΩ

Outlines TO-263 (D2Pak-HV)



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.06	4.83	0.160	0.190
A1	typ. 0.10		typ. 0.004	
A2	2.41		0.095	
b	0.51	0.99	0.020	0.039
b2	1.14	1.40	0.045	0.055
c	0.40	0.74	0.016	0.029
c2	1.14	1.40	0.045	0.055
D	8.38	9.40	0.330	0.370
D1	8.00	8.89	0.315	0.350
D2	2.5		0.098	
E	9.65	10.41	0.380	0.410
E1	6.22	8.50	0.245	0.335
e	2,54 BSC		0,100 BSC	
e1	4.28		0.169	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.02	1.68	0.040	0.066
W	typ. 0.02	0.040	typ. 0.0008	0.002

All dimensions conform with and/or within JEDEC standard.



Thyristor

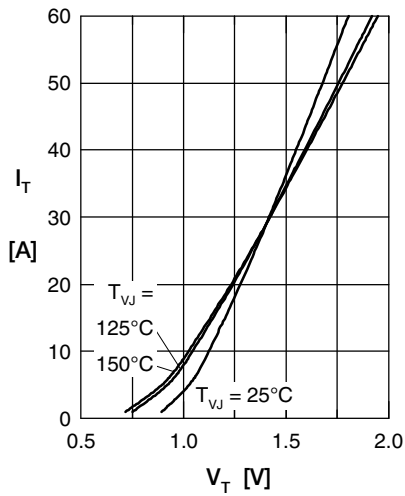


Fig. 1 Forward characteristics

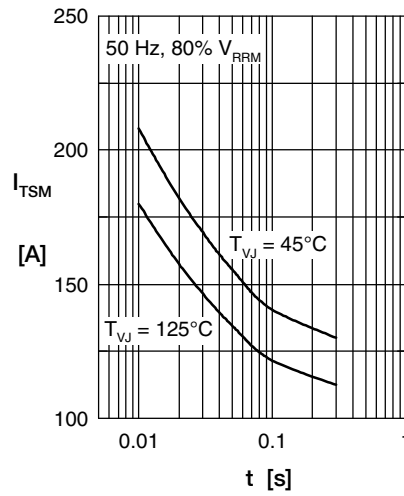


Fig. 2 Surge overload current
 I_{TSM} : crest value, t: duration

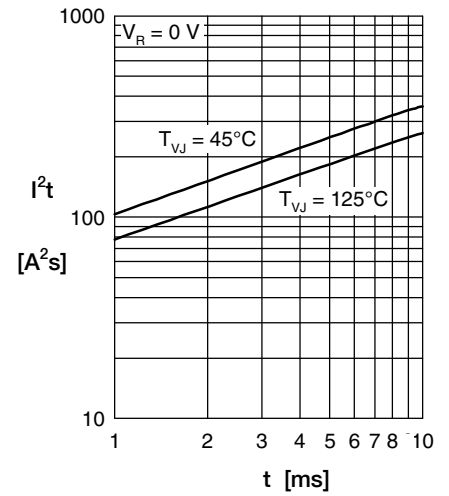


Fig. 3 I^2t versus time (1-10 s)

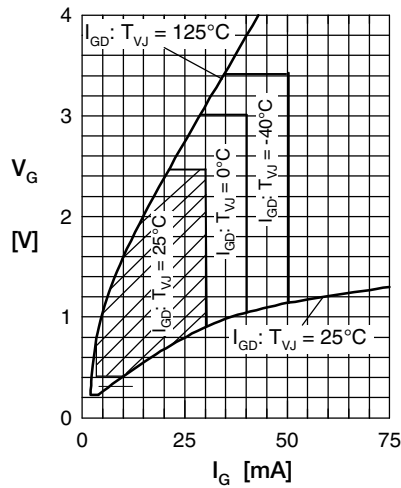


Fig. 4 Gate voltage & gate current
 Triggering: A = no; B = possible; C = safe

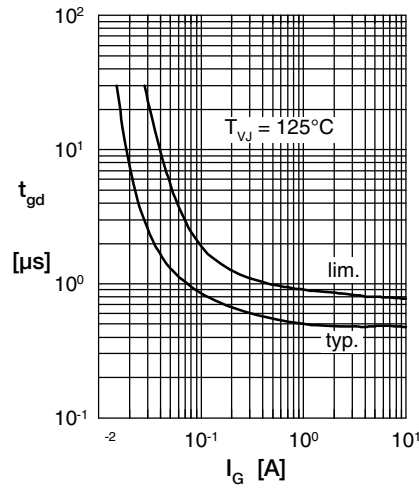


Fig. 5 Gate controlled delay time t_{gd}

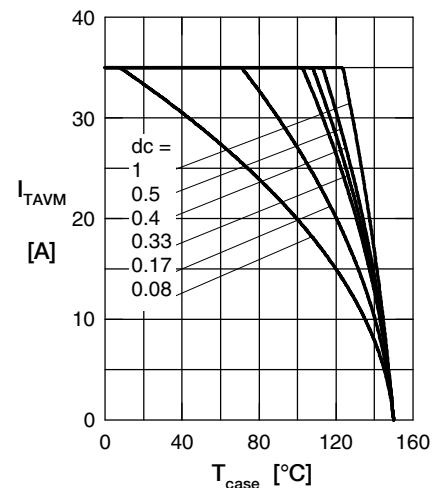


Fig. 6 Max. forward current at case temperature

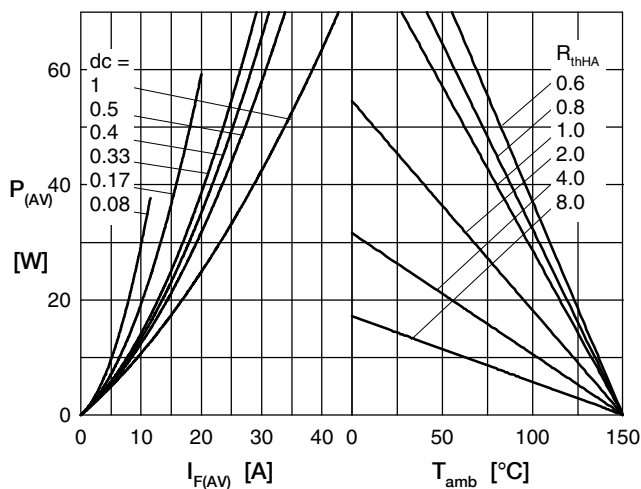


Fig. 7a Power dissipation versus direct output current
 Fig. 7b and ambient temperature

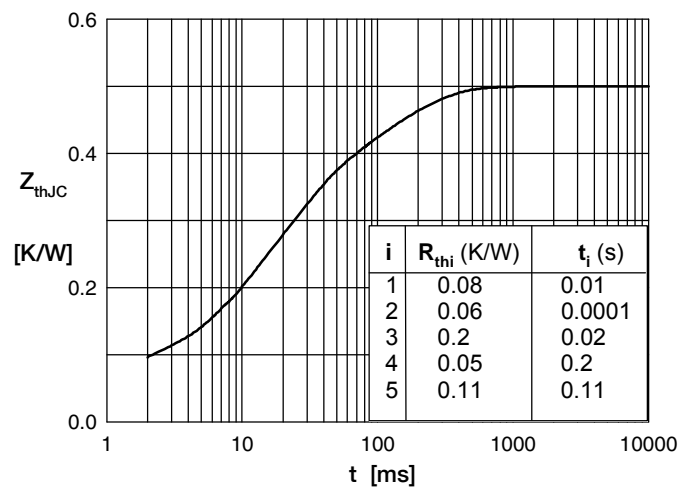


Fig. 7 Transient thermal impedance junction to case